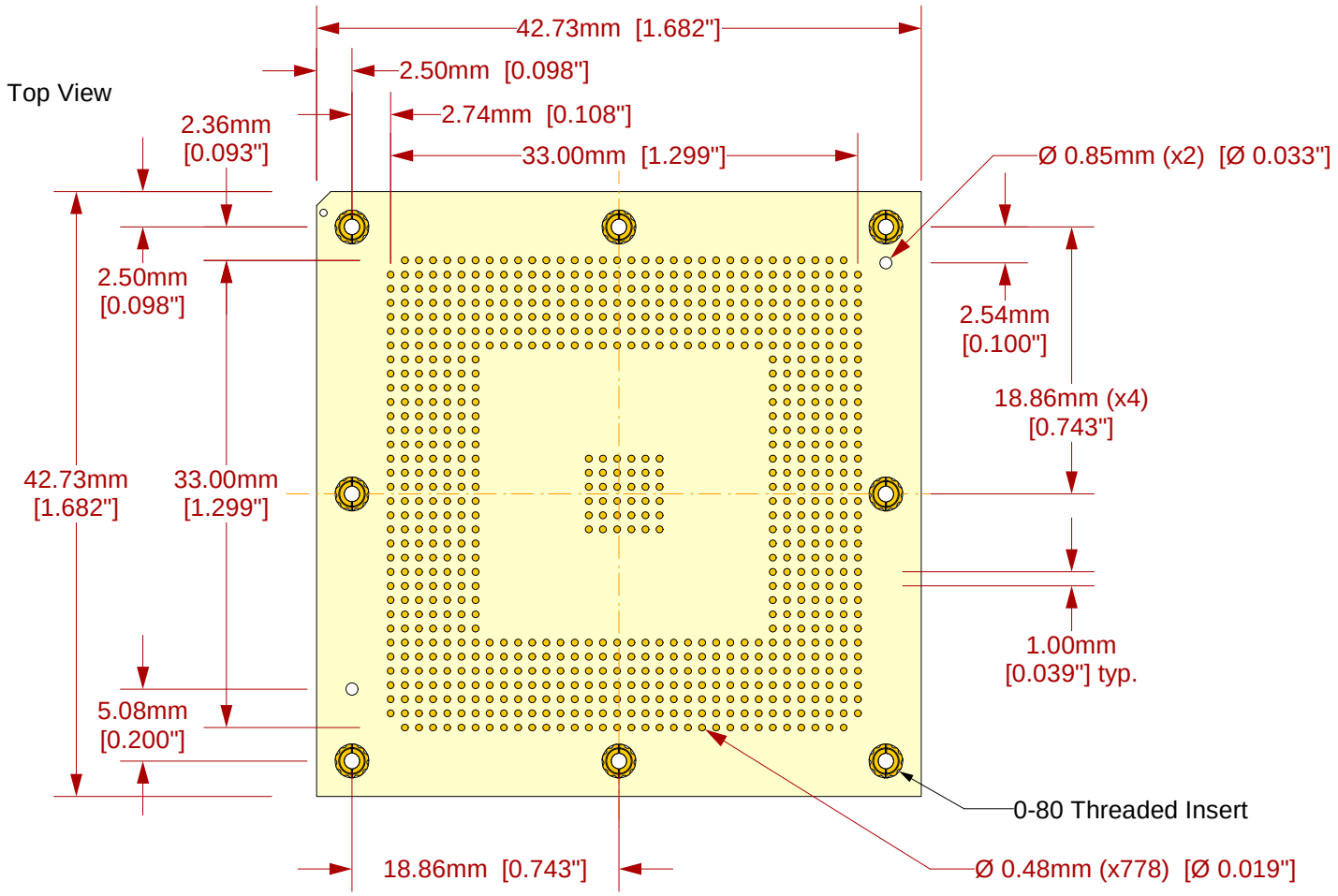

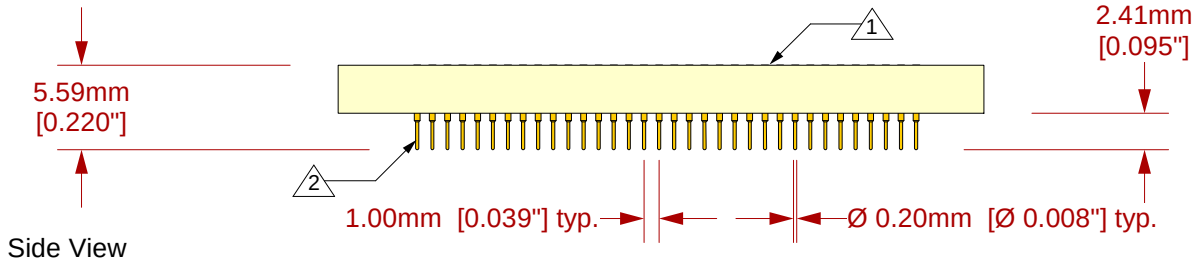

1. Substrate: 3.18mm ±0.125mm [0.125" ±0.005"]
FR4/G10 or equivalent high temp material.
Non-clad.

2. Pin: Brass - PS-2
Plating: 10u" Au over 50u" Ni min.

Description: Giga-snaP BGA SMT land socket
788 position surface mount land pattern to terminal pins (1.0mm centers, 34x34 array). To be used with GHz sockets.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA788B-05 Drawing	Status: Released	Scale: 2:1	Rev: B
© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 9/25/06	
	File: LS-BGA788B-05 Dwg	Modified: 11/12/09 MT/MR	